

# austriamicrosystems introduces ?More Than Silicon? initiative

## Medical Design Technology

austriamicrosystems Full Service Foundry business unit today introduced its “More Than Silicon” initiative, a comprehensive service and technology package that goes beyond industry standard foundry services. Foundry customers instantly benefit from access to leading edge technology add-ons, advanced packaging services and dedicated support engineers to enable first-time-right designs.

The “More Than Silicon” offering provides austriamicrosystems’ foundry customers access to leading edge 3D-IC integration using austriamicrosystems’ patented Through Silicon Via technology (TSV). This advanced TSV technology enables the smallest form factors and addresses a variety of markets demanding 3D integration of CMOS ICs, photo sensors, power devices or MEMS components required in automotive, industrial & consumer applications. Foundry customers using the austriamicrosystems TSV concept immediately benefit from a significantly reduced form factor, systems cost reduction and utmost flexibility in IC and sensor arrangement. The leading edge technology add-on package also features a broad memory portfolio, including SRAM, ROM, BIST structures, One-Time-Programmable (OTP) and fully automotive qualified high reliability non-volatile memories (EEPROM and FLASH).

The “More Than Silicon” package comprises dedicated customer support for specialty foundry projects throughout the entire product value chain, including project definition, design, tape out, prototyping and high volume production. Highly skilled and experienced engineers provide consulting services such as design and layout reviews, ESD and EMC consultancy, Place & Route and test program development for wafer sort and final test. Wafer Level Chip Scale Packaging (WL-CSP) is now available as well as assembly services for commonly used ceramic and plastic packages.

*“Requirements for leading edge analog products have gone beyond the first-time right silicon design. The integration of the IC with advanced analog packaging and post-processing technologies is a must to bring a new breed of analog products to the market. austriamicrosystems’ “More Than Silicon” initiative uniquely supports these requirements and provides fabless design houses with access to special libraries and IP blocks, leading edge technology add-ons and dedicated support engineers,”* said **Thomas Riener**, Senior Vice President and General Manager of austriamicrosystems' Full Service Foundry business unit. *“Foundry customers instantly benefit from our new “More Than Silicon” initiative, which is a clear commitment to our customers to help them with manufacturing their complete analog IC product.”*

## About austriamicrosystems

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austriamicrosystems' business unit Full Service Foundry has successfully positioned itself in the analog/mixed-signal foundry market offering well-established RF CMOS, High-Voltage CMOS, BiCMOS, SiGe-BiCMOS and embedded EEPROM processes. With superior support during the design phase, high-end tools and experienced engineers, austriamicrosystems succeeds to be an attractive analog foundry partner especially for fabless design houses.

austriamicrosystems is a leading designer and manufacturer of standard and customized high-performance analog ICs in the areas of power management, sensors & sensor interfaces and mobile infotainment. Complemented by its full service foundry services, the company focuses on the communications, industrial & medical and automotive markets. austriamicrosystems leverages almost 30 years of expertise in low power and high accuracy to provide industry-leading products, operating worldwide with more than 1,000 employees with its own state-of-the-art manufacturing and test facilities. austriamicrosystems is listed on the SIX Swiss Exchange in Zurich (ticker symbol: AMS).

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